

A

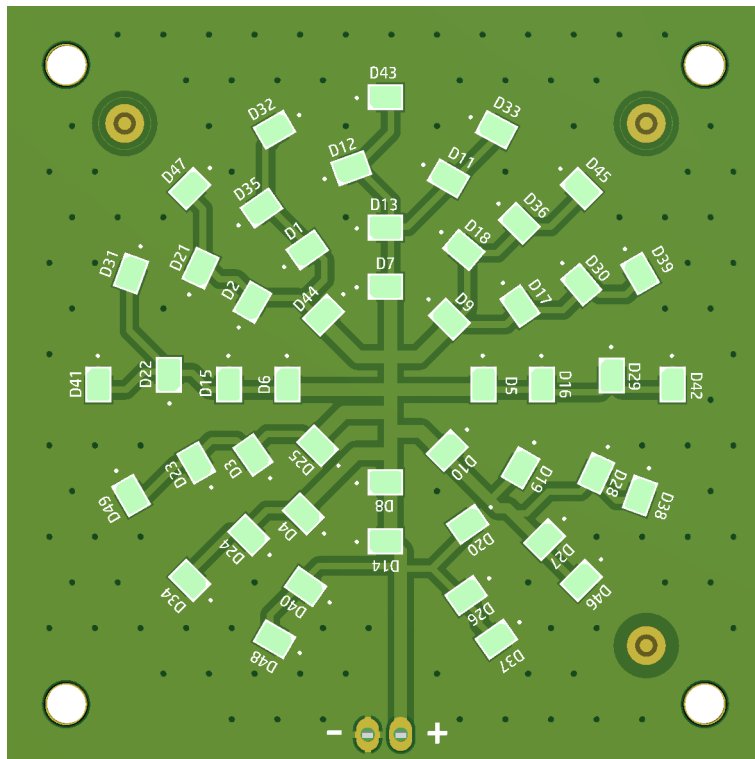
B

C

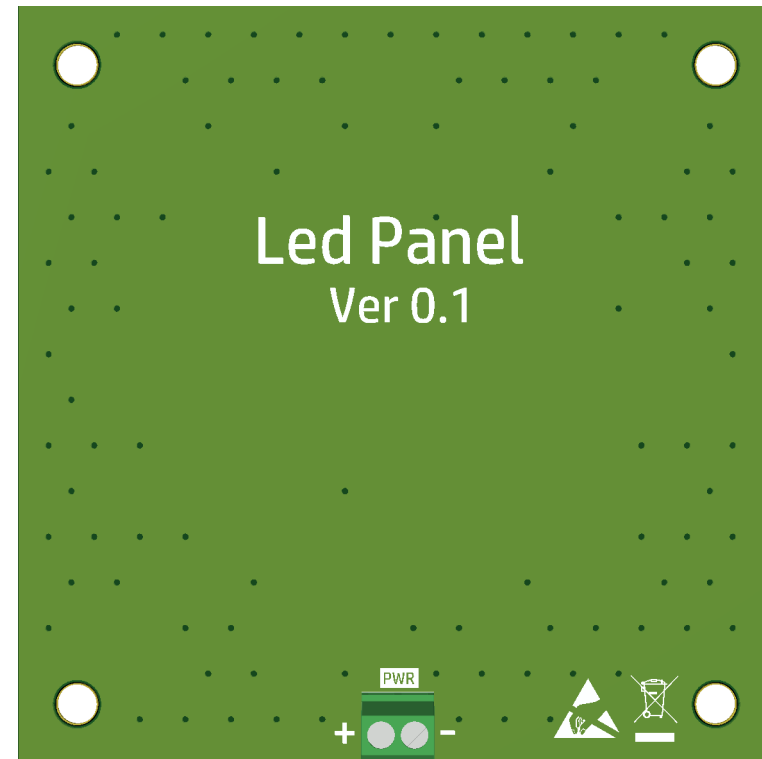
D

Led Panel

Realistic View-TOP



Realistic View-BOTTOM



A

B

C

D

A

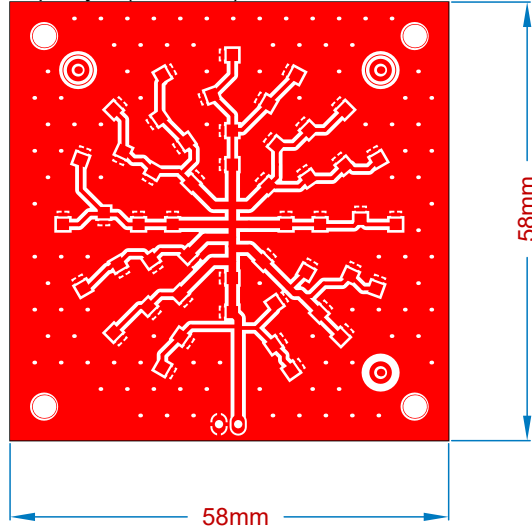
B

C

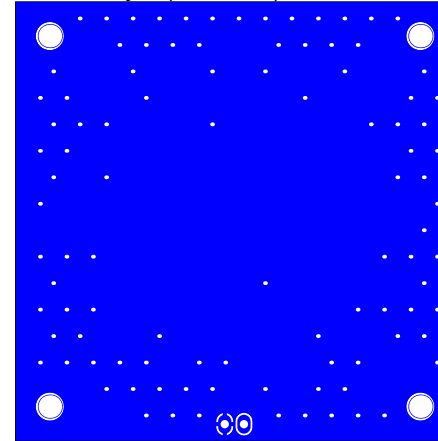
D

FABRICATION AND ASSEMBLY VIEW

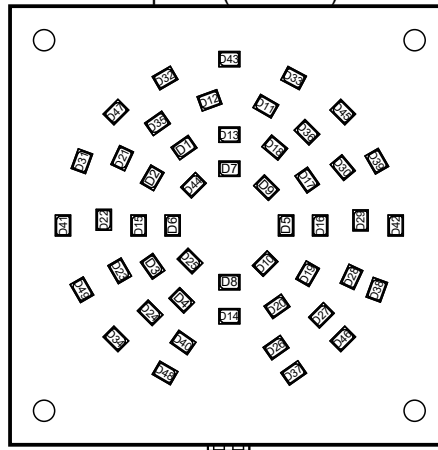
Top Layer (Scale 1:1)



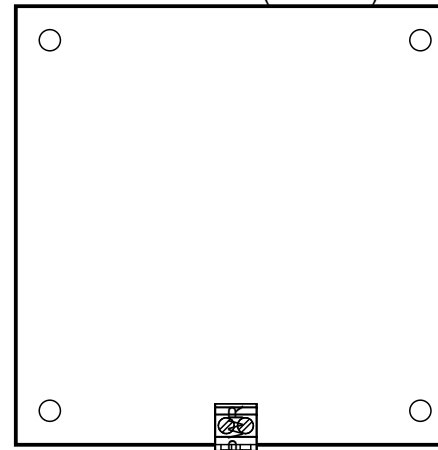
Bottom Layer (Scale 1:1)



View from Top side (Scale 1:1)



View from Bottom side (Scale 1:1)



A

B

C

D

A

B

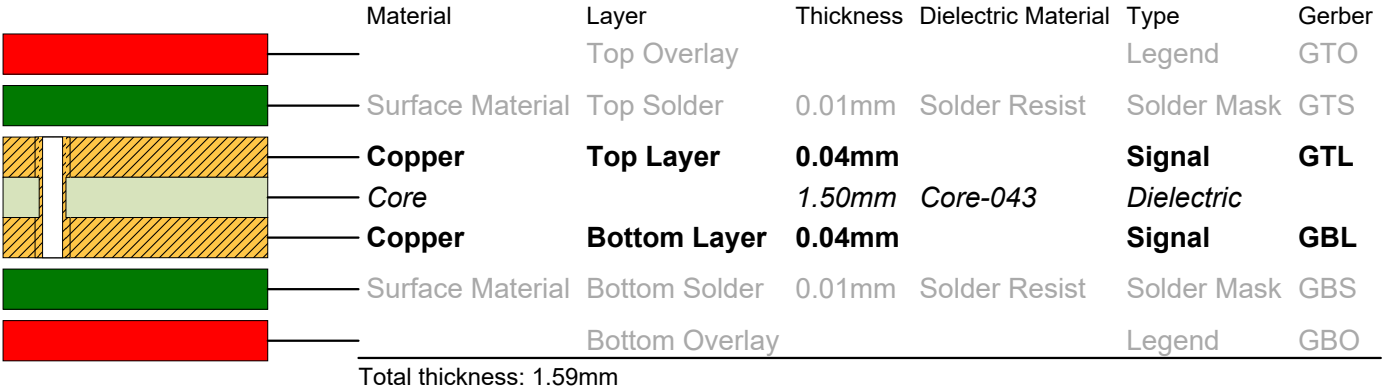
C

D

1

1

Layer Stack Legend



2

2

Drill Table

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via / Pad	Pad Shape
○	2	1.10	Plated	Round	Top Layer - Bottom Layer	Pad	Rounded
□	4	3.00	Plated	Round	Top Layer - Bottom Layer	Pad	Rounded
▽	99	0.50	Plated	Round	Top Layer - Bottom Layer	Via	

A

B

C

D

A

B

C

D

Fabrication and Assembly Notes

FABRICATION NOTES: UNLESS OTHERWISE SPECIFIED.
BOARD NAME: Led Panel
1. FABRICATE PER IPC-6012A CLASS 2.
2. FOR BOARD THICKNESS AND IMPEDANCE DETAILS REFER STACKUP DOCUMENT.
3. SURFACE FINISH: IMMERSION SILVER
4. SOLDERMASK ON BOTH SIDES OF THE BOARD SHALL BE LPI
5. SILK SCREEN LEGEND TO BE APPLIED PER LAYER STACKUP USING WHITE NON-CONDUCTIVE EPOXY INK.
6. THIS PRINTED WIRING BOARD IS DESIGNED WITH A MINIMUM CONDUCTOR WIDTH AND SPACING OF 0.35MM AND 0.25MM
7. TRACE WIDTH SHOULD BE ACCURATELY ETCHED. MAX TOLERANCE +/- 1 MIL
8. ALL DIMENSIONS ARE IN MM UNLESS OTHERWISE SPECIFIED.

ASSEMBLY NOTES
Board Name: Led Panel
Ver: 0.1
1. Assemble in accordance with IPC-A-610, current revision, Class 2.
2. Solder electrical connections per latest revision of IPC J-STD-001.
3. This assembly contains ESD sensitive components. Handle per ANSI/ESD S20.20.
4. RoHS compliance required: Yes.
5. Mark with current assembly revision.
6. Mount components with polarity and orientation as shown on component designators/silkscreen.